



EMB1MN THRU EMB6MN

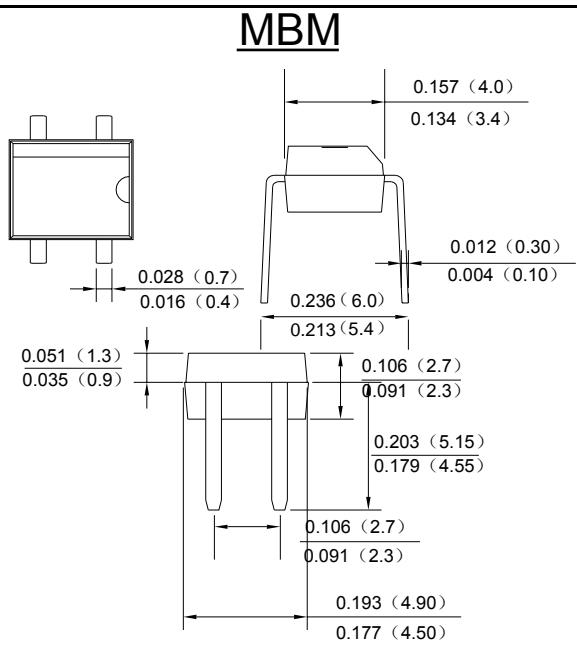
SINGLE PHASE 0.5AMP SUPER FAST GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-25A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case: Reliable low cost construction utilizing molded plastic technique
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	EMB1MN	EMB2MN	EMB4MN	EMB6MN	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RPM}	100	200	400	600	V
	V _{RWM}					
	V _{DC}					
RMS Reverse Voltage	V _{RMS}	70	140	280	420	V
Average Rectified Output Current (Note 1)@T _A =40°C	I _O	0.5				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	25				A
Forward Voltage per element @IF=0.5A	V _{FM}	0.95		1.25	1.75	V
Peak Reverse Current @T _A =25°C At Rated DC Blocking Voltage @T _A =125°C	I _R	5.0 500				uA
Maximum reverse recovery time (Note 3)	T _{RR}	35				ns
Typical Junction Capacitance per leg	C _J	13				pF
Typical Thermal Resistance per leg (Note 4)	R _{θJA}	70				°C/W
	R _{θJL}	20				
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150				°C

Note:1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Reverse Recovery Test Conditions: IF=0.5A, IR=1A, Irr=0.25A.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

